



Protecting your ICs from hostile environment



High Power



Environment space qualified packages

FACILITIES IN NORTH AMERICA CAMBRIDGE (MD) & SAN DIEGO (CA) AND IN FRANCE (BOLLÈNE)

PRODUCTION OF

- Ceramic materials
- Assembly, glass to metal
- Ceramic packages
- Plating (thin layer)

SPECIAL MATERIALS AND ALLOYS

Kovar, CuW, Mo, CuMo, Al, AlGr, AlDia, AlC, Ti, CPC, SCMC, TPG, BeO

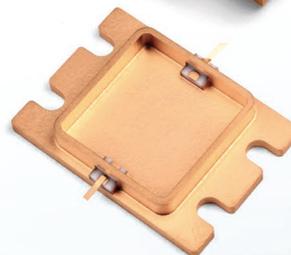
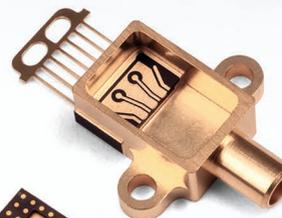
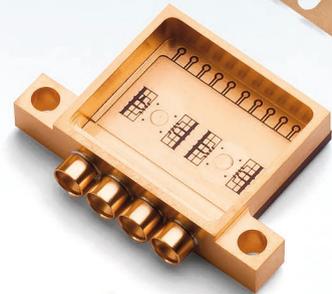
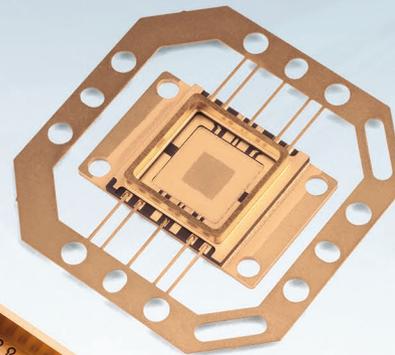
PLATING

- Gold
- Nickel
- Silver
- Copper

RF PRODUCTS

METAL AND HTCC PACKAGES

- High reliability
- High Bandwidth capabilities
- High Power management
- MCM & SIP
- C-QFN
- Flange



PRODUCT FAMILIES

- Chip Carrier
- SMD RF
- Power RF
- MCM
- Opto-Hyper
- Glass Bead
- BGA

FREQUENCY CAPABILITIES

S, C, X, Ku, K, Ka, Q and V Bands

